Appln. No.: 09/772,421

Amendment Dated October 1, 2003 Reply to Office Action of July 8, 2003

<u>Amendments t the Claims:</u> This listing of claims will replace all prior versions, and listings, of claims in the application

Listing of Claims:

1. (Currently Amended) A bonding tool for bonding a wire to a substrate, the bonding tool having a body and a working tip coupled to one end of the body, and comprising:

an orifice extending along a longitudinal axis of the body and the working tip and having a conical portion adjacent the working tip; and

a polymer coating disposed over at least a portion of a <u>non-polymeric</u> surface of the conical portion of the orifice.

- 2. (Original) A capillary bonding tool according to claim 1, wherein the coating extends along an entire length of the orifice.
- 3. (Original) A capillary bonding tool according to claim 2, wherein the coating is applied to at least a portion of an exterior surface of the working tip.
- 4. (Original) A capillary bonding tool according to claim 1, wherein the coating is disposed over at least a portion of an exterior surface of the working tip.
- 5. (Original) A capillary bonding tool according to claim 1, wherein the coating is disposed over an exterior surface of the working tip and the body.
  - 6. (Canceled)
- 7. (Previously Presented) A capillary bonding tool according to claim 1, wherein the coating is at least one of i) a polymer, ii) an Alumina, iii)  $Si_3N_4$ , iv) silica, v) a combination of 12% silica and 88% Alumina, and vi a Diamond like carbon (DLC).
- 8. (Currently Amended) A bonding tool for bonding a wire to a substrate, the bonding tool having a body and a working tip coupled to one end of the body, and comprising:

an orifice extending along a longitudinal axis of the body and the working tip and having a conical portion adjacent the working tip; and

a coating disposed over at least a portion of a <u>non-polymeric</u> surface of the conical portion of the orifice,

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wherein the coating is a polymer disposed along an interior surface of the orifice and one of i) an Alumina, ii)  $Si_3N_4$ , iii) silica, iv) a combination of 12% silica and 88% Alumina, and v) a Diamond like coating (DLC) disposed along an exterior portion of the orifice.

- 9. (Original) A capillary bonding tool according to claim 1, wherein the coating has a substantially uniform thickness.
- 10. (Currently Amended) A bonding tool for bonding a wire to a substrate, the bonding tool having a body and a working tip coupled to one end of the body, and comprising:

an orifice extending along a longitudinal axis of the body and the working tip and having a conical portion adjacent the working tip; and

a polymer coating disposed over at least a portion of a <u>non-polymeric</u> surface of the conical portion of the orifice,

wherein the coating has a substantially uniform thickness of up to about 2.0 microns.

- 11. (Canceled)
- 12. (Original) A capillary bonding tool according to claim 1, wherein the body of the bonding tool has a substantially cylindrical shape.
- 13. (Original) A capillary bonding tool according to claim 1, wherein the coating is one of polyolefine and parylene.
- 14. (Original) A capillary bonding tool according to claim 1, wherein the coating is formed by vapor phase deposition.
- 15. (Original) A capillary bonding tool according to claim 1, wherein the coating is formed by one of chemical vapor deposition and physical vapor deposition.
- 16. (Original) A capillary bonding tool according to claim 1, wherein the coating is formed by immersing the bonding tool in a coating material.
- 17. (Withdrawn) A method of manufacturing a capillary bonding tool for bonding a fine wire to a substrate, the method comprising the steps of:

forming a cylindrical body;

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forming a taper at a first end of the body;
forming an orifice extending along a longitudinal axis of the body; and coating at least a portion of the orifice with a polymer.

- 18. (Withdrawn) The method according to claim 17, wherein the coating step forms a substantially uniform continuous coating having a thickness of up to about 2.0 microns.
- 19. (Withdrawn) The method according to claim 17, wherein the coating step forms a substantially uniform continuous coating having a thickness of at least about 0.1 micron.
- 20. (Withdrawn) The method according to claim 17, wherein the coating step comprises the steps of:

forming a precursor monomer at a first temperature and a first pressure; and

forming the coating from the precursor monomer at a second temperature and pressure.

- 21. (Withdrawn) The method according to claim 20, wherein the first temperature is about 690°C, the first pressure is about 0.5 torr, the second temperature is about 25°C, and the second pressure is about 0.1 torr.
- 22. (Withdrawn) The method according to claim 20, wherein the precursor monomer is formed from a di-Para-Xylyene dimer vaporized at about 150°C and about 1.0 torr followed by a pyrolesis at about 690°C and about 0.5 torr.
- 23. (Withdrawn) The method according to claim 17, wherein the capillary is formed by i) one of direct ceramic dye pressing and ii) injection molding, and machined to a final shape by one of i) grinding and ii) Electro discharge machining.
  - 24. (Withdrawn) A bonding tool for bonding a wire to a substrate, comprising: a body portion;

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a working tip coupled to one end of the body;

an orifice extending along a longitudinal axis of the body and the working

tip;

a first coating disposed over at least a portion of a surface of the orifice; and

a second coating disposed over at least a portion of an exterior surface of

the body.

25. (Withdrawn) A capillary bonding tool according to claim 24, wherein the first coating is a polymer and the second coating is other than a polymer.

26. (Withdrawn) A capillary bonding tool according to claim 25, wherein the second coating is one of an alumina and  $Si_3N_4$ .

27. (Withdrawn) A method of manufacturing a capillary bonding tool for bonding a

fine wire to a substrate, the method comprising the steps of:

forming an orifice extending along a longitudinal axis of the bonding tool;

coating at least a portion of the orifice with a polymer; and

coating at least a portion of an exterior surface of the bonding tool with a non-

polymer coating.

28. (Currently Amended) A bonding tool for bonding a wire to a substrate, the

bonding tool having a body and a working tip coupled to one end of the body, and comprising:

an orifice extending along a longitudinal axis of the body and the working tip and having a conical portion adjacent the working tip; and

a polymer non-conductive coating disposed over at least a portion of a non-

polymeric surface of the conical portion of the orifice.